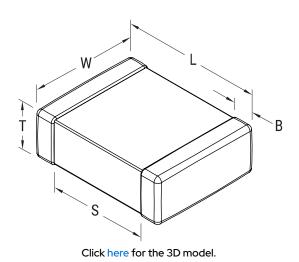




SMD Comm X8G HT150C Flex, Ceramic, 3,600 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	15 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1206	
L	3.3mm +/-0.4mm	
W	1.6mm +/-0.35mm	
Т	0.78mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	
В	0.6mm +/-0.25mm	

W	1.6mm +/-0.35mm	
Т	0.78mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	
Packaging Specifications		

Specifications		
Capacitance	3,600 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	1%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity 10000	Dissipation Factor		
		Aging Rate	

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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